

UL Solutions serves manufacturers across the entire PCB supply chain:

#### **Industrial laminates**

- Rigid
- Ultrathin
- Flexible
- High-density interconnect
- Metal-based
- Metal-clad laminates

#### Coatings

#### and solder masks

- Solder resist
- Conformal coating
- Films
- Liquids
- Photoimageable
- UV curable

#### PCBs

- Single-layer
- Multilayer
- HybridFlexible
- Flex-rigid
- Metal-based

#### **Assemblies**

Traceability program



## Optimized market access

UL Solutions offers a full range of testing and certification services to

UL Standards and many other international, national and regional requirements, including American Society for Testing and Materials (ASTM), Association Connecting Electronics Industries (IPC) and International Electrotechnical Commission (IEC).

In each targeted market, UL Solutions can help you gain the confidence you need to succeed. The scope of our services include:

#### **Precertification services**

- Consulting
- Planning
- Project optimization
- Quotation

## Safety testing and certification

- PCB compliance
- Laminate and coating compliance
- Production board testing
- Assembly traceability

#### Performance and reliability testing

- Reflow simulation
- Thermal cycling and thermal stress
- Failure analysis
- Interconnect stress testing (IST)
- Signal integrity testing
- Conductive anodic filament growth (CAF)
- Coating testing conformal coating and solder mask

#### Overall testing capability

- Advanced analytical
- Chemical
- Electrical
- Environmental
- Flammability
- Mechanical and physical
- Coatings

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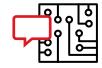
Early communication with a UL Solutions engineer

Certification project scope reviewed by a UL Solutions engineer

Detailed list of project documentation and requirements

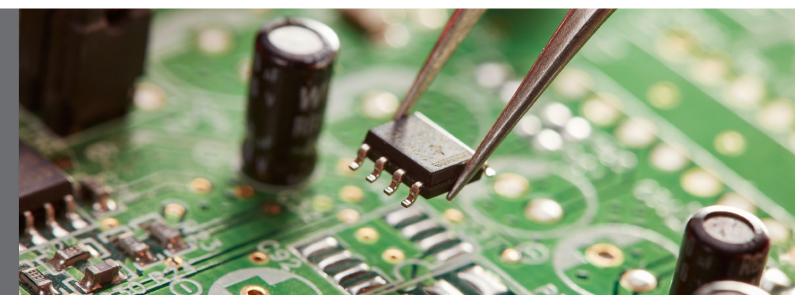
## Precertification services

## Paving the way for future compliance



UL Solutions precertification reviews are designed to shorten the path to certification. Through an advanced technical consultation with a UL Solutions engineer, we'll help make sure you fully understand the sample requirements and test program ahead of time, thus avoiding potential costly delays. Precertification reviews are also eligible for a 100 percent credit toward certification costs.\*

\*The credit is only applicable for the Scope of Services and test program agreed upon in the associated precertification project. The credit is valid for a maximum of 120 days after the completion of the precertification project (may be less based on country-specific business laws and practices). Additional terms may apply.





# Safety testing and certification

## Setting the benchmark



UL Solutions is the only organization that issues PCB safety Standards. You can make use of our technical expertise in safety testing and certification services; this process can help achieve regulatory compliance as well as communicate to

customers that your product has been tested to the benchmark of product safety.

UL Solutions extensive relationships across the entire PCB supply chain have manufacturers turning to us when they are looking for reliable components from trustworthy sources. Your customers will also value how UL Solutions assists them to eliminate duplicate testing of the finished end products when they contain UL Recognized components.

All testing can be conducted in UL Solutions-accredited laboratories or in your own qualified facilities.



#### **UL Standards for PCBs**

For UL Solutions recognition of PCB safety, the following Standards apply:

- UL 796 Printed Wiring Boards for standard rigid, metal-based and HDI PCBs
- UL 796F Flexible Materials Interconnect Constructions for flexible and flex-rigid PCBs
- UL 746E Polymeric Materials for industrial laminates and materials used in PCBs
- UL 746F Polymeric Materials for flexible dielectric film materials
- UL 94 for flammability of plastic materials

#### **UL Standards related to PCBs**

Certification is driven by end-product requirements. The actual PCB ratings required are dependent on the end-product application and how the PCB will be employed. Always check with the end-product manufacturer to determine what ratings they require. Many end-product standards, such as the following, require UL Recognized PCBs:

- UL 60950 Information technology equipment
- UL 60065 Audio and video equipment
- UL 62368 ITE and audio/video equipment
- UL 60601 Medical equipment
- UL 60335 Appliances
- UL 61010 Industrial control equipment
- UL 8750 LED equipment

#### **UL Recognized = enhanced market acceptance**

PCB components and materials that are recognized by UL Solutions are known to have undergone the industry's most stringent safety testing and follow-up program. UL Recognized components are listed in UL Solutions' Online Certifications Directory, UL.com/database and the UL iQ<sup>TM</sup> database iq.UL.com/pwb. These allow your customers to search and identify the components and materials they need to complete their subassemblies or end products.



UL also offers Quick-Turn Certification of production boards to UL 796. This service allows for faster time to market by testing actual production boards instead of requiring specialized samples that first need to be created. The service is limited to the tested build of materials, construction stack-up and trace layout.

# Performance and reliability testing

#### **Empowering the PCB industry**



Advances in today's electronic applications depend upon sophisticated PCB technology. If it doesn't work, the whole product will be compromised. Increase your customers' confidence by demonstrating the PCB is not only compliant to regulatory safety requirements but also tested to perform reliably.

Our performance testing and certification programs apply to a comprehensive range of PCB components and materials.

Every program can be customized to match the PCB application and meet your business needs.

#### Thermal and environmental conditioning

Thermal and environmental conditioning accelerates degradation of the PCB to determine material and structural integrity via microsection analysis and destructive and nondestructive testing.

#### **Accelerated Thermal Cycling (ATC)**

ATC from high to low temperature ranges simulates environmental exposure on critical circuits and is used to evaluate and predict the fatigue life of PCB's.

Thermal expansion coefficients between components, PCB's and PCB structure can result in solder and embedded copper strain inducing fatigue or failure of the printed circuit board.

#### Interconnect stress testing (IST)

IST speeds up temperature cycling to detect susceptibility to early failure, and thereby increases product reliability. It is 12 times faster than in an air-to-air thermal oven, creating the opportunity for greater testing output.

#### Signal integrity testing

Signal integrity testing (SIT) determines the amount of signal propagation caused by the characteristics of the materials, conductors and accompanying structures on the PCB. Losses in the signal will result in frequency-dependent attenuation.

#### Conductive anodic filament (CAF) growth

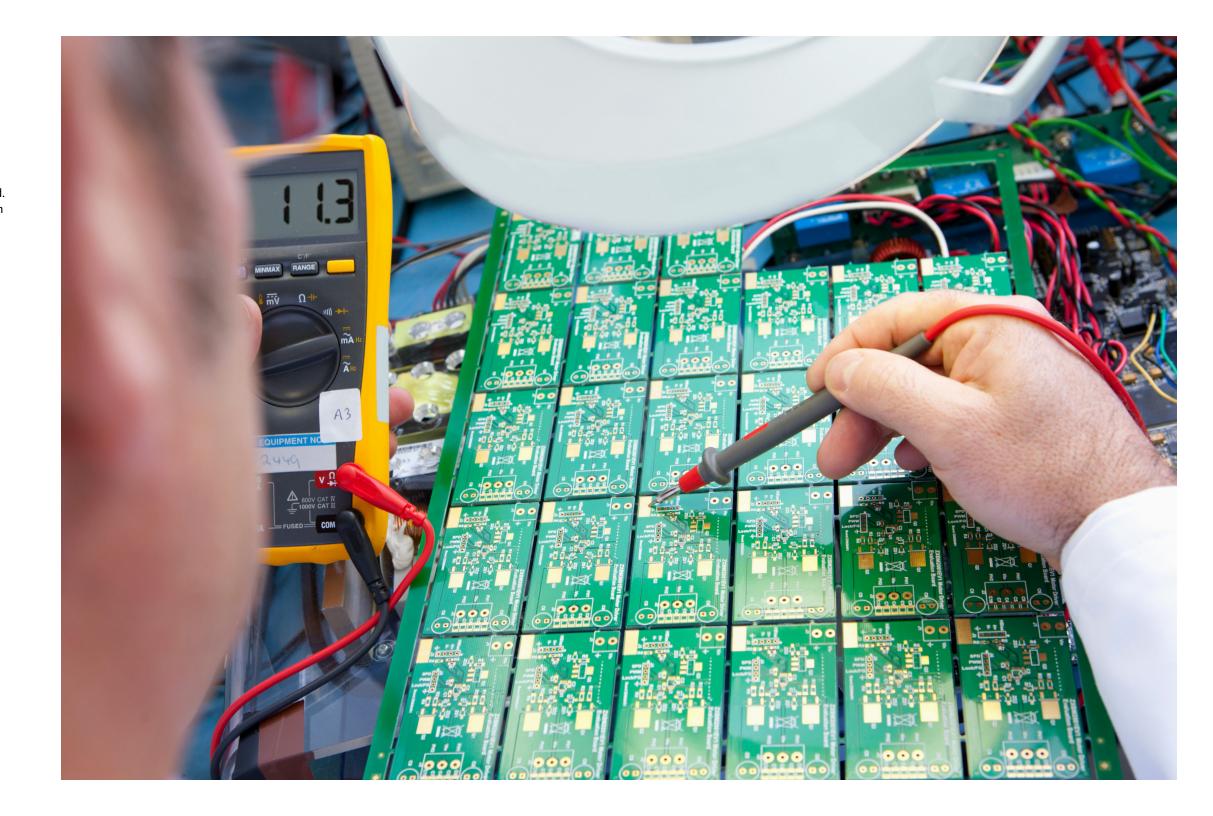
The need for CAF testing is ever increasing with overall product sizes and conductor spacings being reduced. CAF failure involves the growth or "electrochemical migration" of copper in a PCB. This unintentional growth typically bridges two oppositely biased copper conductors resulting in a short circuit. Catching and correcting this potential failure can substantially lengthen product lifespans.

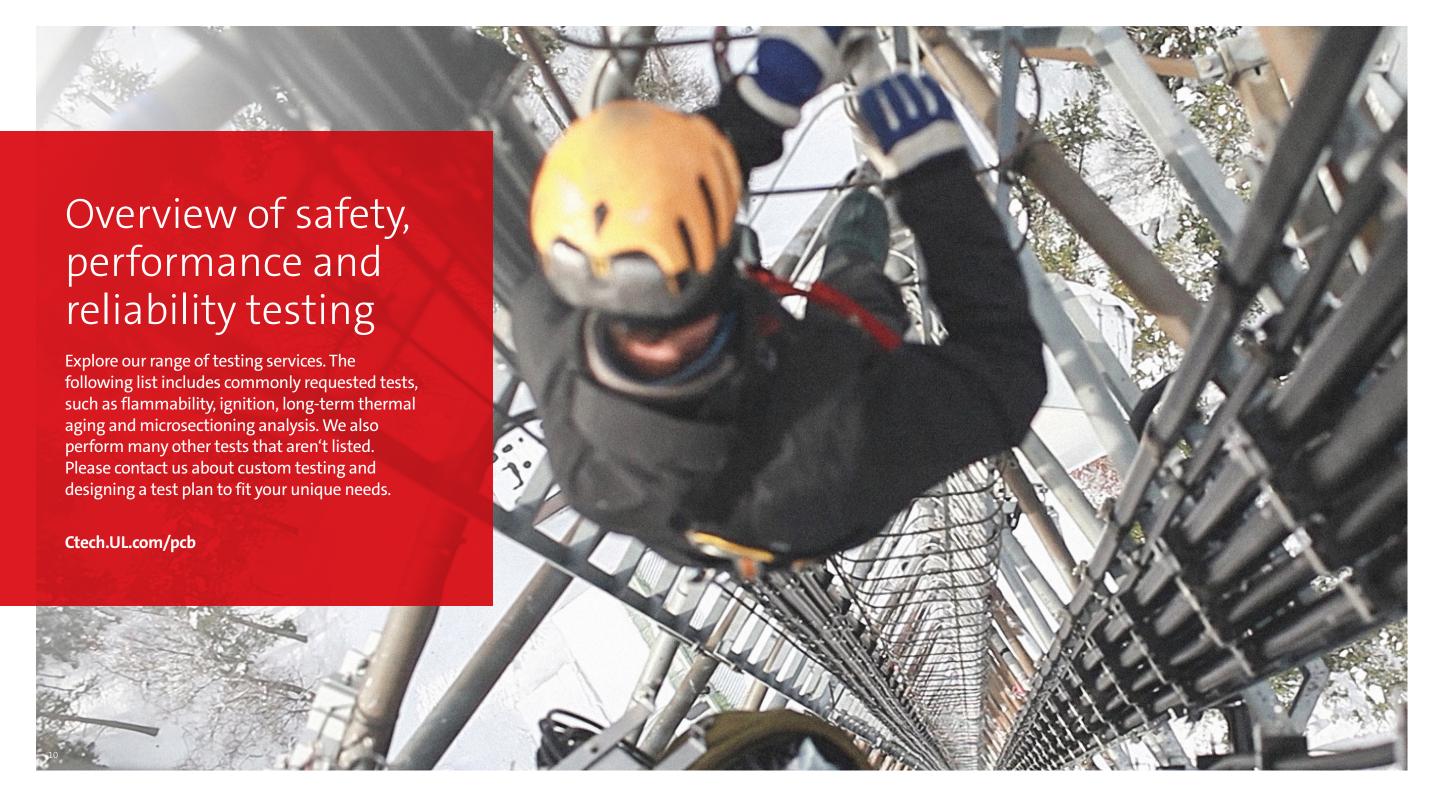
#### Conformal coating and solder mask testing

Conformal coatings are applied to electronic circuits to provide a barrier to moisture and contamination and to provide electrical insulation.

UL Solutions offers a full suite of coating testing services, including:

- UL 746E evaluations
- IPC-CC-830: Qualification and performance testing of electrical insulating compounds for printed circuit assemblies
- IPC-SM-840: Qualification and performance specification of permanent solder mask and flexible cover materials
- IEC-60664-3: Insulation coordination for equipment within lowvoltage systems, via the use of coatings to achieve insulation coordination of printed board performance and assemblies.





## Advanced analytical techniques

- Atomic absorption spectroscopy (AAS)
- Ash content
- Differential scanning calorimetry (DSC), glass transition temperature
- Dynamic X-ray (2D or 3D X-ray)
- Dynamic mechanical analysis (DMA)
- Energy dispersive X-ray spectroscopy (EDS)
- Extractions
- Failure analysis (F/A)
- Fourier transform infrared spectroscopy (FTIR)
- Gas chromatography/mass spectroscopy (GC/MS)
- Gel content
- Ignition loss
- Inductively coupled plasma spectroscopy/optical emission spectroscopy (ICP/OES)
- Ion chromatography (IC)
- Microwave digestion
- Scanning electron microscopy (SEM)
- Thermogravimetric analysis (TGA)
- Thermomechanical analysis (TMA)
- X-ray (live-time, nondestructive inspection of package)
- X-ray fluorescence (XRF)

#### **Chemical testing**

- Alloy composition
- Bisphenol-A content
- Chemical resistance/solder resistance
- Density/specific gravity
- Flammability
- Hazardous substance analysis
- Heavy metals/lead content
- Ion chromatography (IC)
- Organotin content
- pH
- Phthalate content
- Restriction of hazardous substances (RoHS)
- Solder paste slump test
- Spitting of flux-cored wire solder
- Viscosity

### **Environmental testing**

- Accelerated aging
- Altitude
- Autoclave (pressure vessel)
- Conductive anodic filament (CAF)
- Chemical resistance
- Cold impact
- Corrosion resistance
- Drop/impact
- Drop resistance
- Electromigration/electrochemical migration (ECM)
- Flammability
- Fluid resistance
- Fungus resistance
- Humidity (cycling or steady state)
- Hydrolytic stability
- Immersion
- Interconnect stress test
- Ingress protection (IP)
- Moisture and insulation resistance (MIR)
- Moisture absorption
- Moisture resistance
- Oxygen index
- Salt spray/fog
- Solvent resistance
- Temperature/humidity
- Thermal aging
- Thermal cycling
- Thermal shock
- Thermal stress
- Time to delamination
- UV exposure
- Vicat softening point
- Water spray
- Water vapor transmission/water absorption
- Weathering

## Flammability testing

- Burning rate ASTM D 229, sections 61-66 (method I/vertical)
- Burning rate ASTM D 635 (horizontal)
- Burning rate FAA 25.853b5 (horizontal)
- Burning rate FMVSS 302 (49CFR571) (horizontal)
- Burning rate ISO 3795 (horizontal)
- Burning rate UL 94 HB (horizontal)
- Burning rate UL 94 HBF (horizontal)
- Burning rate UL 94 5V (vertical)
- Burning rate UL 94 V (vertical)
- Burning rate UL 94 VTM (vertical)
- Flammability, small component, UL 1694
- Oxygen index ASTM D 2863 (Procedure A/Test Method A)

## **Electrical testing**

- Arc resistance
- Capacitance
- Comparative tracking index (CTI)
- Conductive anodic filament growth (CAF)
- Conductivity
- Dielectric breakdown
- Dielectric constant/permittivity
- Dielectric strength
- Dielectric withstanding voltage (DWV)
- Dissipation factor/loss tangent
- Electromigration/electrochemical migration (ECM)
- High-current arc ignition (HAI)
- High-voltage arc tracking
- Hot-wire ignition
- Inclined plane tracking
- Interconnect stress test
- Resistance
- Signal integrity testing (SIT)/SET2DIL/TDR
- Surface insulation resistance (SIR)/insulation resistance
- Volume and surface resistivity

#### **Mechanical and physical** property testing

- Abrasion
- Adhesion
- Bend testing
- · Bond strength
- · Bow and twist
- Breaking strength
- Brittleness
- Coating thickness
- · Coefficient of friction
- Coefficient of thermal expansion (CTE)
- Compression set
- Compression properties
- Compressive strength
- Cross-section analysis
- Cure
- Deflection under load
- Deformation temperature
- Dimensional stability
- Dynamic mechanical analysis (DMA)
- Elongation
- Flexural strength and modulus

- Glass transition temperature by thermal mechanical analysis (TMA)
- Hardness
- Impact strength
- Impact resistance
- Lap shear strength
- Mechanical cycling
- Mechanical strength
- Microsectioning
- Peel strength
- Plating thickness
- Rework simulation
- Shear properties Shear strength
- Softening point
- Specific gravity/density
- Tear resistance
- Tensile impact
- Tensile strength
- Tensile properties

Young's Modulus

Tension and compression

- Coatings conformal coating and solder masks
- Abrasion (Taber)
- Adhesion
- Appearance
- Coating thickness
- Cure time and temperature
- Dielectric strength
- Dielectric withstanding voltage (DWV)
- Electrochemical migration
- Flammability
- Flexibility
- Flourescence
- Fourier tansform infrared spectroscopy (FTIR)
- Fungus resistance
- Hardness
- Hydrolytic stability
- Insulation resistance
- Lap shear
- Moisture insulation resistance
- Peel strength
- Q-resonance
- Resistance to chemicals, solvents and cleaning agents
- Shelf life
- Tensile strength
- Thermal shock
- Thermal stress
- Visual requirements



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